TOSHIBA Photointerrupter Infrared LED + Phototransistor

TLP830(F)

Track "00" Sensor For Floppy Disk Drive Detection Of Sub-Scanning Quantity By Image Scanner

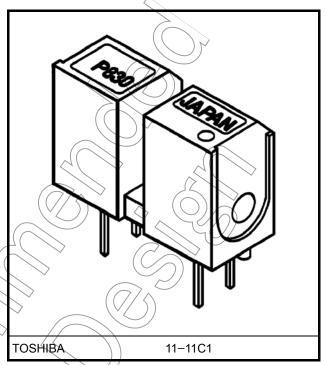
Various Position Detection Sensor

TLP830(F) is a photointerrupter which uses a high-radiant power GaAs LED and a fast-response Si phototransistor. The device is high resolution with a narrow slit pitch.

- Small package: 7.4 mm (H), 4.5 mm (D)
- Printed wiring board direct mounting type (with a locating pin).
- Board thickness: 1mm or less
- Short lead type enabling automated mounting
- Gap: 2mm
- High resolution: Slit width 0.15mm
- High current transfer ratio: IC/IF = 3% (min)
- High temperature operation: $T_{opr} = 95$ °C (max)
- Material of the package:

Polybutylene terephthalate (UL94V-0, black color)

• Detector side is of visible light cut type.



Weight: 0.4 g (typ.)

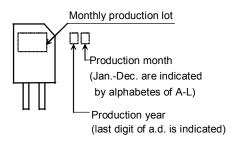
Absolute Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	Rating	Unit	
	Forward current	l _E <	(50/)	mA	
LED	Forward current derating Ta > 25°C	ΔIF/°C	-0.33	mA / °C	
	Reverse voltage	VR	5	V	
	Collector-emitter voltage	V _{CEO}	> 35	V	
Detector	Emitter-collector voltage	V _{ECO}	5	V	
	Collector power dissipation	Pc	75	mW	
	Collector power dissipation derating (Ta > 25°C)	ΔPc/°C	-1	mW/°C	
	Collector current	// Ic	50	mA	
Operating temperature range		T _{opr}	-30 to 95	°C	
Storage te	mperature range	T _{stg}	-40 to 100	°C	
Soldering temperature (5 s)		T _{sol}	260	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Product Indication



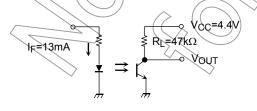
Operating Ranges

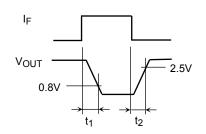
Characteristic	Symbol	Min	Тур.	Max	Unit
Supply voltage	V _{CC}	_	5	24	<i>/</i> v
Forward current	lF	_	- <	25	mA
Operating temperature	T _{opr}	-10	-	75	°C

Opto Electrical Characteristics (Ta = 25°C)

						~		
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit	
	Forward voltage		V _F	J _E = 10 mA ((//	(1).00	1.15	1.30	V
LED	Reverse current		I _R	V _R =5V	<u> </u>	_	10	μА
	Peak emission wavelength		λР	1 _F = 10 mA	_	940	_	nm
	Dark current		Ip(V _{CE} = 24 V, I _F = 0	_	_	0.1	μА
Detector	Peak sensitivity wavelength		AP			870	1	nm
	Current trans	fer ratio	/ c/l _F	V _{CE} = 2 V, I _F = 10 mA	3		20	%
Coupled	Collector-em saturation vol	//	V _{CE} (sat)	I _F = 20 mA, 1 _C = 0.3 mA	_	0.1	0.35	V
	Switching times	Rise time	t _r	$V_{CC} = 5 \text{ V}, I_C = 1 \text{ mA}$	_	15	-	
		Fall time	tr _	$R_L = 1 \text{ k}\Omega$		15	_	6
		Response time (1)	t ₁	V _{CC} = 4.4 V, I _C = 13 mA	_		80	μS
		Response time (2)	/ ^t 2	$R_L = 47 \text{ k}\Omega$ (Note)	_	_	800	

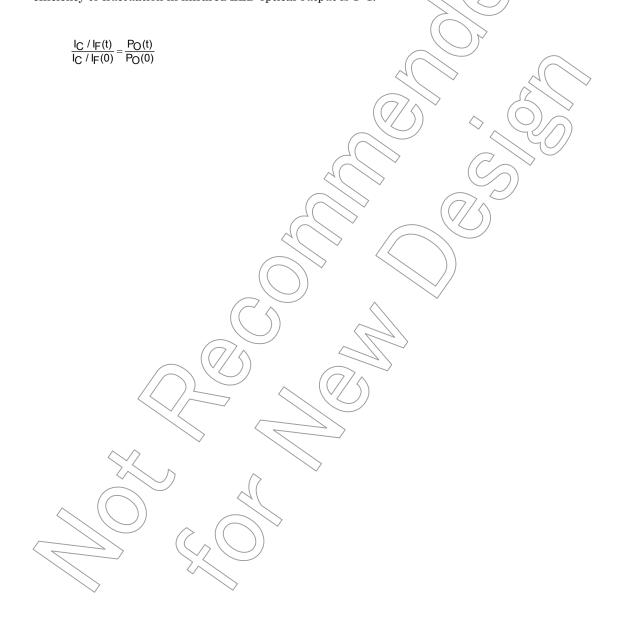
Note: t₁, t₂ test condition





Precaution

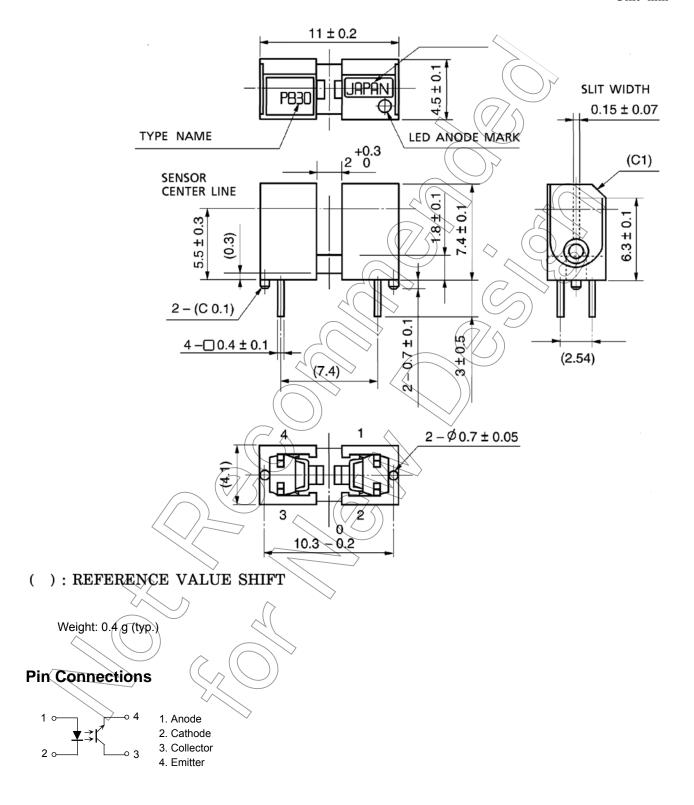
- 1. If the chemical are used for cleaning, the soldered surface only shall be cleaned with chemicals avoiding the whole cleaning of the package.
- 2. The container is made of polybutylene terephthalate. Oil or chemicals may cause melting or cracks. Check the environment carefully before installing.
- 3. Shall be mounted on an unwarped surface.
- 4. A visible light cut-off type photo transistor which blocks light with frequencies of 700nm or above is used. However, the device cannot block ambient light with a wavelength of 700nm or more or sunlight. Install avoiding the disturbance light.
- 5. Conversion efficiency falls over time due to the current which flows in the infrared LED. When designing a circuit, take into account this change in conversion efficiency over time. The ratio of fluctuation in conversion efficiency to fluctuation in infrared LED optical output is 1:1.

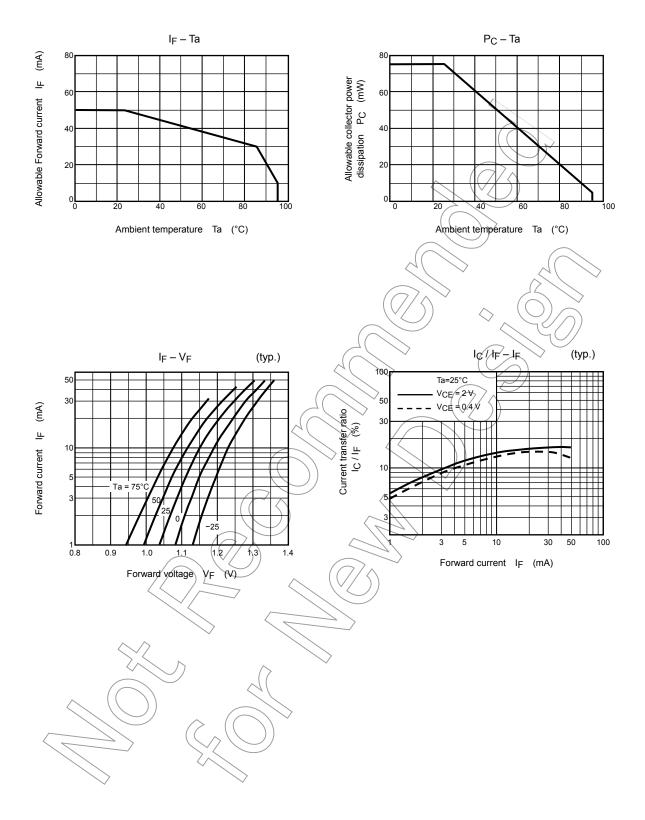


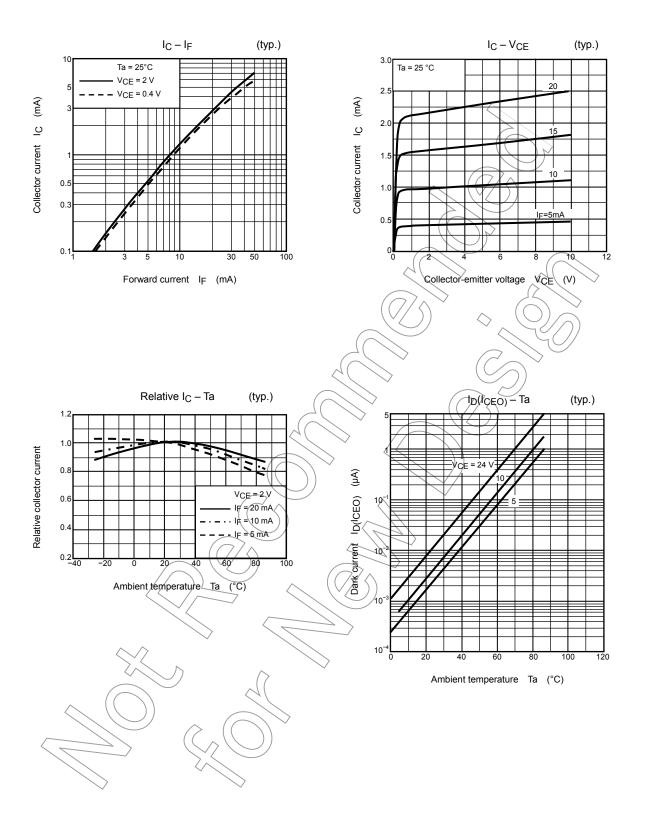
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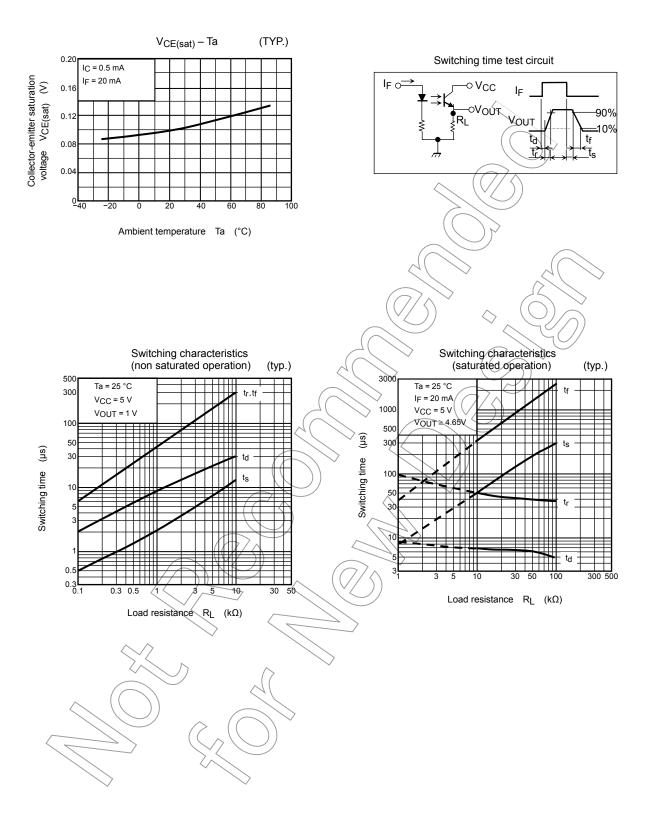
Outline: TOSHIBA

Unit: mm

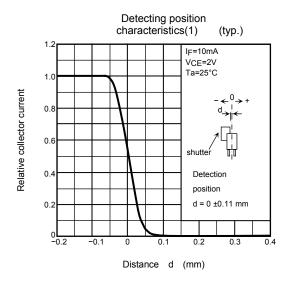


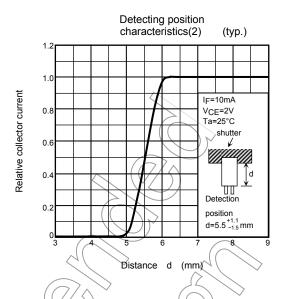






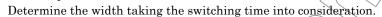
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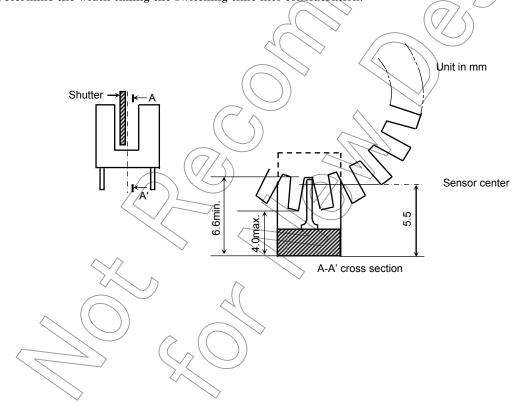




Positioning Of Shutter And Device

To operate correctly, make sure that the shutter and the device are positioned as shown in the figure below. The shit pitch of the shutter must be set wider than the slit width of the device.





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